



Amendment Under 37 C.F.R. §1.116  
Expedited Handling Procedure  
Box AF  
Group Art Unit: 2503

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re patent application of

K. Kata et al. ✓

Serial No.: 08/533,207

Group Art Unit: 2503

Filed: September 25, 1995

Examiner: M. Prenty ✓

For: PROCESS FOR MANUFACTURING SEMICONDUCTOR DEVICE  
AND SEMICONDUCTOR WAFER

Assistant Commissioner for Patents  
Box AF  
Washington, D.C. 20231

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DEC 24 1997

GROUP 2500

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AMENDMENT UNDER 37 C.F.R. §1.116

Sir:

In response to the Office Action mailed September 23, 1997, please  
amend the above-identified application as follows:

IN THE SPECIFICATION:

✓ On page 8, line 28, after "chips" delete ", chip electrodes formed on the  
opposite side of the semiconductor chips and interconnection layers connecting  
the chip electrodes and the bump electrodes, wherein the chip electrodes are not  
located directly across the chip from the bump electrodes".

IN THE CLAIMS:

12/23/1997 MGORDON 00000015 08533207  
01 FC:102 164.00 DP

- 1 5. (Three Times Amended) A semiconductor wafer having a plurality of  
2 semiconductor chips, comprising bump electrodes simultaneously formed into a

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